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<p>Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)</p>		<i>Complete If Known</i>	
		Application Number	09/527,931
		Filing Date	March 17, 2000
		First Named Inventor	Gaetan L. Mathieu
		Group Art Unit	3726
Examiner Name	Rick K. Chang		
No. of Refs.: 192	Attorney Docket No.	P114-US	

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	172.	“Membrane Probe Technology for MCM Known-Good-Die”, article, HP Japan, 1994 (MJC1975640-47)				Yes
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OTHER PRIOR ART – NONPATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ⁶	Copy Enclosed
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	188.	Karl F. Zimmerman, "SiProbe-A New Technology for Wafer Probing", proceedings, 1995, International Test Conference, pages 106-112 (MJC1975652-58).		Yes
	189.	United States International Trade Commission, In the Matter of Certain Probe Card Assemblies, Components Thereof and Certain Tested DRAM and NAND Flash Memory Devices and Products Containing Same, Inv. No. 337-TA-621, Respondent Micronics Japan Co., LTD's First Supplemental Response to Complainant FormFactor, Inc's First Set of Interrogatories (Nos. 25-29), Exhibit 5, March 14, 2008.		Yes
	190.	United States International Trade Commission, In the Matter of Certain Probe Card Assemblies, Components Thereof and Certain Tested DRAM and NAND Flash Memory Devices and Products Containing Same, Investigation No. 337-TA-621, Supplemental Response of Phicom Corporation to Complainant FormFactor, Inc.'s First Set of Interrogatories (Nos. 26-30), Exhibit 29, March 14, 2008		Yes
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* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication

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** Reference cited in parent application US Serial Nos. 09/527,931. (See 1.98(d).)

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